

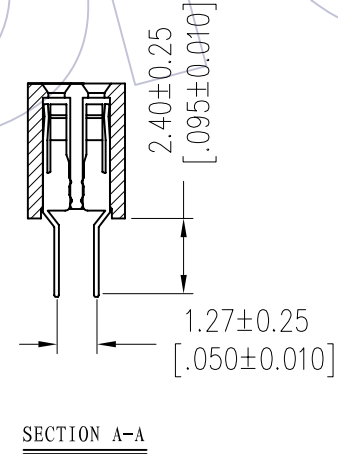
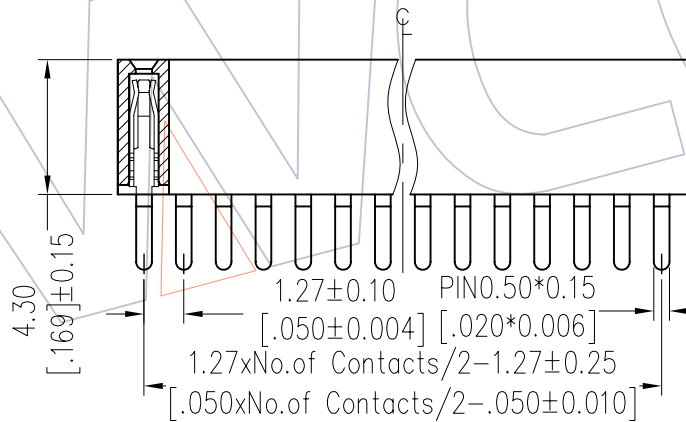
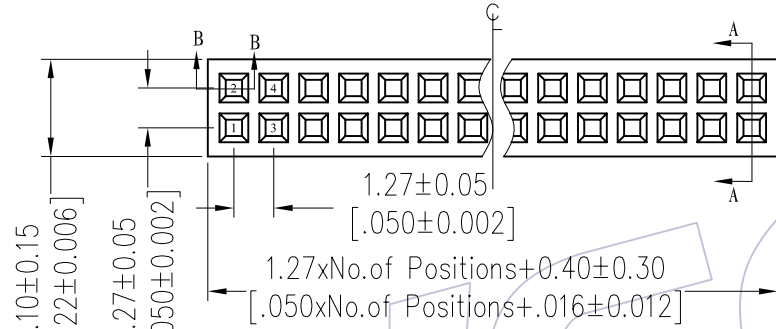
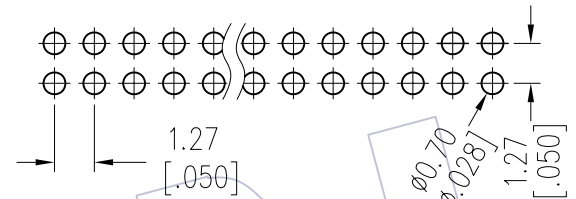
# HSF

**NOTES:**

Current Rating: 1.0AMP  
 Contact Resistance: 20mΩ Max  
 Withstand Voltage: 500V AC/DC  
 Insulation Resistance: 1000MΩ Min  
 Operation Temperature: -40°C to +105°C

Contact Material: Phosphor Bronze  
 Contact plating: Au Or Sn over Ni  
 Insulator Material: PA9T+30%G.F UL94V-0

Recommended P.C.B Layout (Top Side)  
 (PCB BOARD TOLERANCE ±0.05)



## Ordering Information

2344-2 XX S XX CUN T 1

No. of Pins per Row: 02-50Pin

Contact Plating:

- G0=Gold Flash
- G3=10μ"Gold
- G4=15μ"Gold
- G5=30μ"Gold
- S0=Gold Flash/Tin
- S3=10μ"Gold/Tin
- S4=15μ"Gold/Tin
- S5=30μ"Gold/Tin
- SN=Tin

Packing:

- T=Tube
- P=Tube+CAP
- R=Tape&Reel+CAP

Item	Pitch	Mating
Standard	1.27	1310/1315/1320/3131/3133/3100
Alternate		

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	OPERATION	DRAW	DATE	SCALE	FIT	PART NO.
				x.x ±0.40	JYHuang	2012/07/09	UNIT	mm	2344-2XXSXXCUNT1
				x.xx ±0.25	CHECK	DATE	SIZE	A4	TITLE:
				x.xxx ±0.15	APPROVE	DATE	SHEET	1/1	FH1.27mm DUAL ROW 180° DIP
				Angle ± 3°			PROJ.	Customer NO.	H=4.30
				DIM TOL					